

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客户: _____

PRODUCT 产品: _____ SAW FILTER _____

MODEL NO 型号: _____ HDF303.825M-T039 _____

PREPARED 编制: _____ CHECKED 审核: _____

APPROVED 批准: _____ DATE 日期: _____ 2008-3-5 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

1. SCOPE

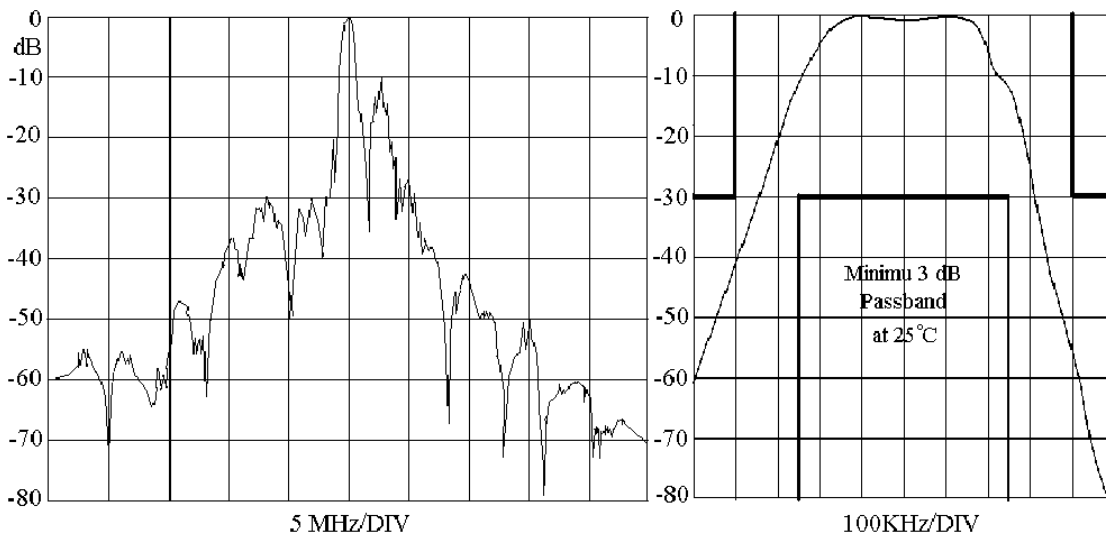
This specification shall cover the characteristics of SAW filter 303.825MHz with used for remote-control security.

2. ELECTRICAL SPECIFICATION

DC Voltage VDC 10V	
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

Electronic Characteristics

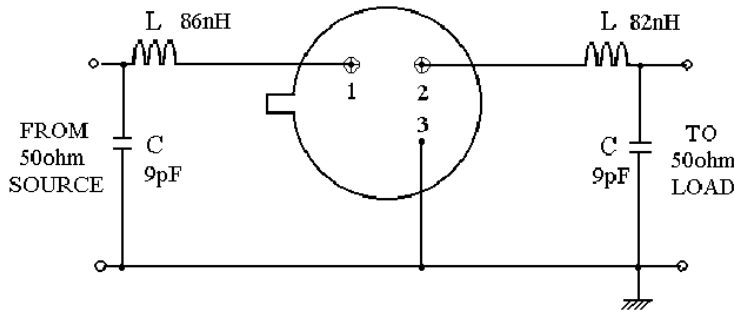
2-1.Type frequency response



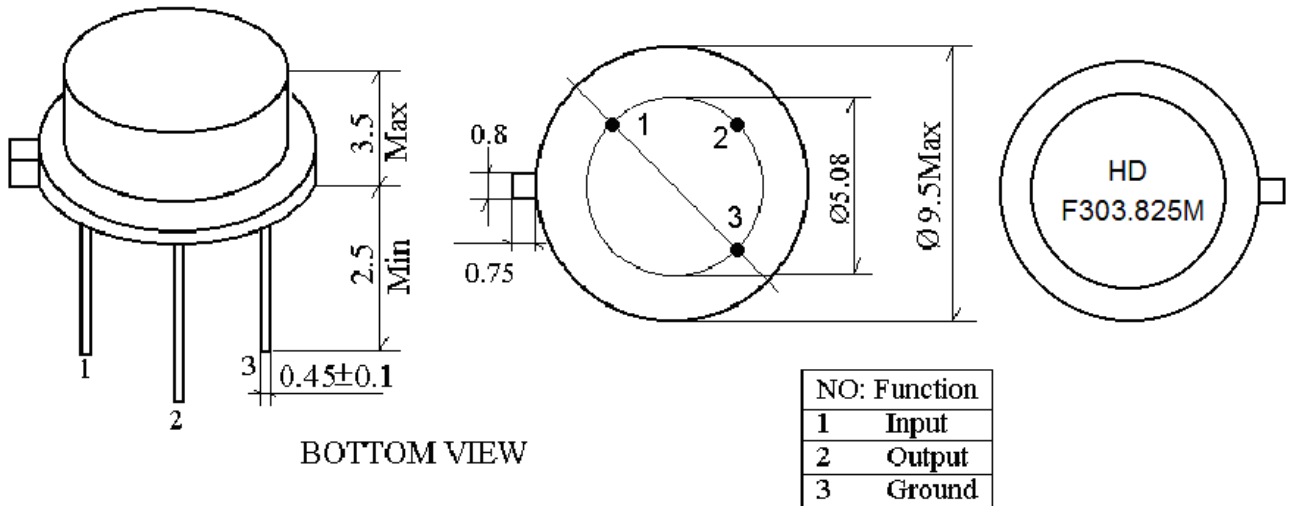
2-2.Electrical characteristics

Characteristic		Sym	Min	Typical	Max	Units
Norminal Frequency		f_c		303.825		MHz
Insertion Loss		IL		3.5	5.0	dB
3dB Bandwidth		BW ₃		600		KHz
Temperature Stability	Turnover Temp.	To	10	25	40	°C
	Turnover Frequency	Fo		f_c		KHz
	Frequecy Temp.Coefficient	FTC		0.032		ppm/°C ²
Frequency Aging Absolute Value during the First Year		fA		10		ppm/yr
DC Insulation Resistance between Any Two Pins			1.0			MΩ
Rejection	at $f_c-21.4$ MHz (Image)		40	50		dB
	at $f_c-10.7$ MHz (Lo)		15	30		
	Ultimate			80		
External Impedance	Shut Capacitance			9		pF

3. TEST CIRCUIT



4. DIMENSION



5. ENVIRONMENTAL CHARACTERISTICS

5-1 Temperature cycling

Subject the device to a low temperature of -40 °C for 30 minutes. Following by a high temperature of +25 °C for 5 Minutes and a higher temperature of +85 °C for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2-2.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260 °C ± 5 °C for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2-2.

5-3 Solderability

Submerge the device terminals into the solder bath at 245 °C ± 5 °C for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2-2.

5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 2-2.

5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 2-2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.